

FMSB30B THRU FMSB30M UMSB

3.0A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER Reverse Voltage - 100 to 1000 V Forward Current – 3.0A

FEATURES

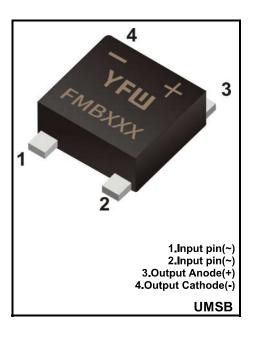
- ♦Fast reverse recovery time
- **♦**Designed for Surface Mount Application
- ♦Glass Passivated Chip Junction
- **♦Low power loss, high efficiency**
- ♦Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

♦Case: UMSB

♦Terminals: Solderable per MIL-STD-750, Method 2026

♦Approx. Weight: 0.234g / 0.00824oz



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	FMSB30B	FMSB30D	FMSB30G	FMSB30J	FMSB30K	FMSB30M	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	٧
Maximum RMS voltage	V _{RMS}	70	140	280	420	560	700	٧
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	٧
Average Rectified Output Current at T _c = 115 °C	l _o	3.0				Α		
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I _{FSM}	90				A		
Forward Voltage per element at 3.0A	V _F	1.1				٧		
Maximum DC Reverse Current @T _A =25°C at Rated DC Blocking Voltage @T _A =125°C	I _R	5.0 200					μΑ	
Typical Junction Capacitance (Note1)	C _j	40				pF		
Maximum Reverse Recovery Time (Note2)	Trr		150		250	50	00	nS
Typical Thermal Resistance (Note3)	Reja Rejc Rejl	65 15 30				°C/W		
Operating and Storage Temperature Range	Tj, Tstg	-55 ~ +150			°C			

⁽¹⁾ Measured at 1 MHz and applied reverse voltage of 4 V D.C

Rev: BDJ

⁽²⁾ Mounted on glass epoxy PC board with 4×1.5"×1.5" $\,^{\circ}$ 3.81×3.81 cm $^{\circ}$ copper pad.

FMSB30B THRU FMSB30M UMSB

Fig.1 Average Rectified Output Current Derating Curve

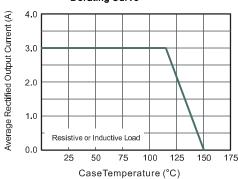


Fig.2 Typical Reverse Characteristics

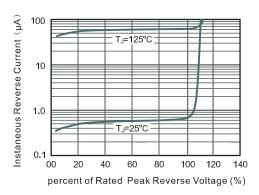


Fig.3 Typical Instaneous Forward Characteristics

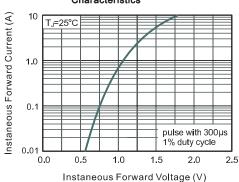


Fig.4 Typical Junction Capacitance

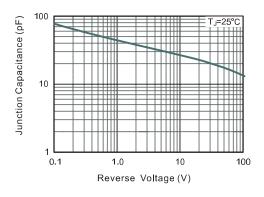


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

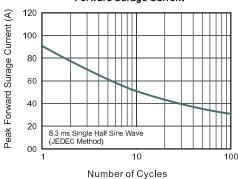
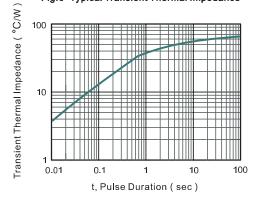
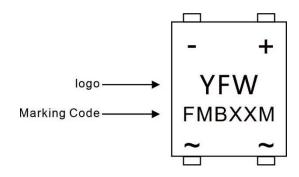


Fig.6- Typical Transient Thermal Impedance





Marking Diagram

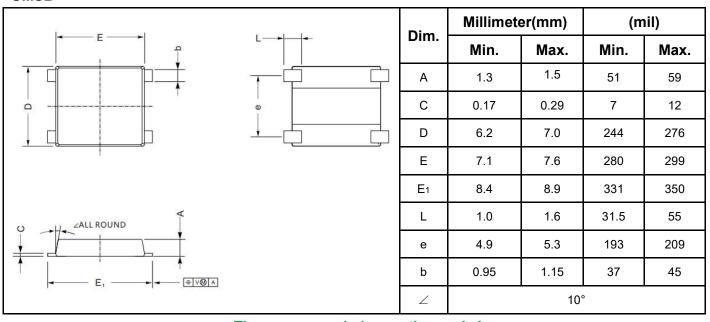


Ordering information

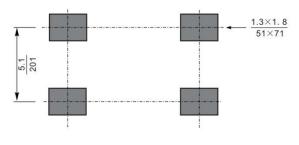
Package	Packing Description	Packing Quantity			
UMSB	Tape/Reel,13"reel	3000PCS/Reel 30000PCS/Carton			

Package Dimensions

UMSB



The recommended mounting pad size



Unit: mm (mil)





Disclaimer

The information presented in this document is for reference only. GuangDong Youfeng Microelectronics Co.,Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise. The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices),YFW or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale. This publication supersedes & replaces all information previously supplied. For additional information, please visit our website https://www.yfwdiode.com, or consult YFW sales office for further assistance.

Rev: BDJ